

What is claimed is:

1. A junction structure for conductive projection,
comprising a conductive projection joined to a conductor
5 portion which is formed on a surface of an insulating layer,
wherein said conductive projection is joined to the
surface of said conductor portion which is formed at the same
level as that of the surface of said insulating layer, and
a root portion of said conductive projection is surrounded
10 by a resin material in a ring form.
2. The junction structure for conductive projection
according to claim 1, wherein said resin material which
surrounds said root portion of said conductive projection is
15 in a fillet form.
3. The junction structure for conductive projection
according to claim 1, wherein said resin material contains
an activator which assists the junction between said conductive
20 projection and said conductor portion when said resin material
is in an uncured state.
4. The junction structure for conductive projection
according to claim 1, wherein said resin material has
25 photocuring property.
5. The junction structure for conductive projection
according to claim 1, wherein said conductive projection
comprises a core portion and a conductive surface layer portion
30 for covering the surface of said core portion.

6. A junction method for conductive projection, comprising the steps of:

forming a conductor portion on an insulating layer in such a way that the surface of said conductor portion is formed
5 at the same level as that of the surface of said insulating layer;

supplying a resin material in an uncured state onto at least a junction plane of said conductor portion to which a conductive projection is joined;

10 disposing said conductive projection on said junction plane which has said resin material supplied thereon; and

heating said resin material and said conductive projection to join said conductive projection to said conductor portion while curing said resin material so as that a root
15 portion of said conductive projection is surrounded by said resin material in a ring form.

7. The junction method for conductive projection according to claim 6, wherein said resin material in an uncured state
20 is supplied onto the entire surfaces of both of said conductor portion and said insulating layer, and cured by exposure while excluding the resin material on said junction plane, said conductive projection is disposed on said junction plane on which said resin material remains uncured, and said resin
25 material and said conductive projection are heated.